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Docket No.: 4066 USA D1/Consilium/Consilium
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
John F. Arackaparambil et al.

Application No.: 10/084,092

Filed: February 28, 2002

Art Unit: 2125

For: COMPUTER INTEGRATED
MANUFACTURING TECHNIQUES

Examiner: Steven R. Garland

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESUBMISSION OF UNACKNOWLEDGED REFERENCES

In response to the Examiner's statement in his Office Action of October 17, 2005, that the Information Disclosure Statement filed December 18, 2003, contained references without publication dates, please find attached a new PTO Form SB-08 containing the appropriate date information. A copy of each of these references is also attached.

In response to Examiner's statement that the Information Disclosure Statement filed April 25, 2003, did not contain required documentation of the references, attorney for the applicant herewith provides an additional copy of the references as submitted on April 25, 2003 (as well as a copy of the stamped postcard indicating previous submission of the references). A clean copy of the Form PTO-1449 is herewith attached.

Applicants respectfully request that the Examiner acknowledge these references on the appropriate forms and return them with the next official action. Any deficiency should be charged to Deposit Account No. 08-0219.

Dated: May 17, 2006

Respectfully submitted,

By 

Scott M. Alter, Registration No. 32,879
Wilmer Cutler Pickering Hale and Dorr LLP
1875 Pennsylvania Avenue, NW
Washington, DC 20006
(202) 663-6000
Attorneys for Applicant



PTO/SB/08a/b (07-05)
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U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/B/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>			Complete if Known		
			Application Number	10/084,092	
			Filing Date	February 28, 2002	
			First Named Inventor	Arackaparambil et al.	
			Art Unit	2125	
			Examiner Name	Steven Garland	
Sheet	1	of	1	Attorney Docket Number	4066 USA D1/Consilium/Consilium

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)			

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)				

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		"NanoMapper wafer nanotopography measurement by ADE Phase Shift." http://www.phase-shift.com/nanomap.shtml . December 9, 2003.	
		"Wafer flatness measurement of advanced wafers." http://www.phase-shift.com/wafer-flatness.shtml . December 9, 2003.	
		"ADE Technologies, Inc. - 6360." http://www.adetech.com/6360.shtml . December 9, 2003.	
		"3D optical profilometer MicroXAM by ADE Phase Shift." http://www.phase-shift.com/microxam.shtml . December 9, 2003.	
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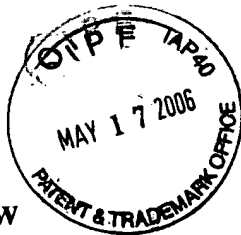
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² Applicant is to place a check mark here if English language Translation is attached.

Examiner Signature		Date Considered	
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HALE and DORR LLP
1455 Pennsylvania Avenue, NW
Washington, DC 20004
(202) 942-8400



Applicant(s): **John F. ARACKAPARAMBIL et al.** Application No.: **10/084,092**
Filing Date: **February 28, 2002** Docket No.: **004066 USA D01/Consilium/Consilium**
Entitled: **Computer Integrated Manufacturing Techniques** **107262.169 SMA/AHK/lrm**

RECEIPT IS ACKNOWLEDGED FOR THE FOLLOWING:

- [X] Supplemental Information Disclosure Statement and 11 PTO-1449 Forms
- [X] 213 References in 5 volumes

**INFORMATION DISCLOSURE
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(PTO-1449)**

ATTY. DOCKET NO.
004066 USA
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GROUP
2121

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						Yes	No
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	3-202710	09/04/91	Japan			X	
	8-23166	01/23/96	Japan			X	
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	10-34522	02/10/98	Japan			X	
	0 869 652	10/07/98	Europe			X	
	WO 99/09371	02/25/99	WIPO			X	
	0 910 123	04/21/99	Europe			X	
	0 932 194	07/28/99	Europe			X	
	WO 00/00874	01/06/00	WIPO			X	
	2000-183001	06/30/00	Japan			X	

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						Yes	No
	1 071 128	01/24/01	Europe			X	
	WO 01/18623	03/15/01	WIPO			X	
	WO 01/25865	04/12/01	WIPO			X	
	434103	05/16/01	Taiwan			X	
	436383	05/28/01	Taiwan			X	
	455938	09/21/01	Taiwan			X	
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<p align="center">OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</p>		
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